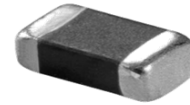


# Chip Bead For EMI Suppression

## CIB/CIM21 Series (2012/ EIA 1008)



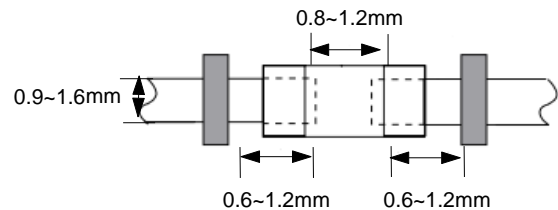
### APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

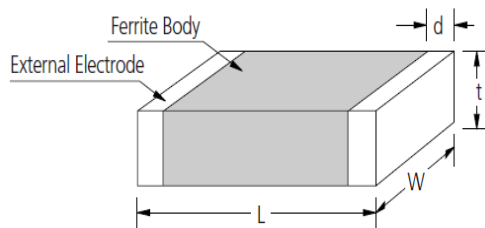
### FEATURES

- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

### RECOMMENDED LAND PATTERN



### DIMENSION



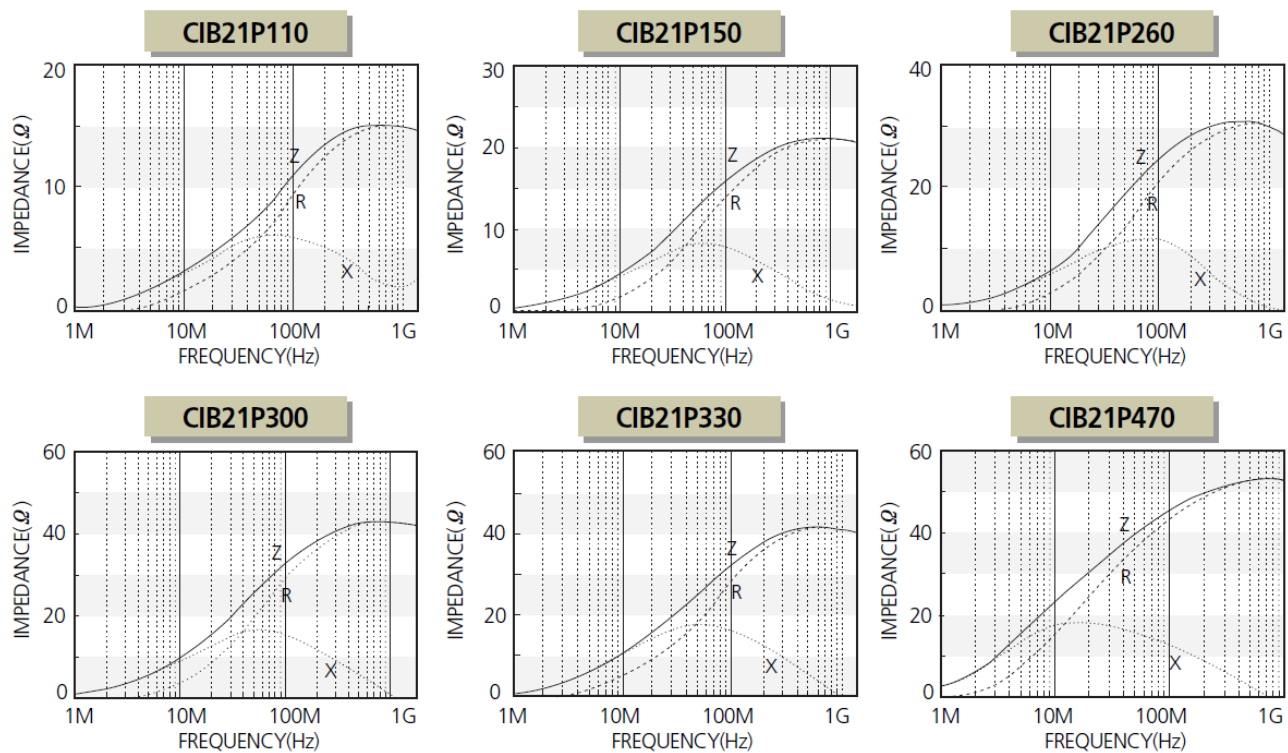
Type	Dimension [mm]			
	L	W	t	d
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2 -0.3

### DESCRIPTION

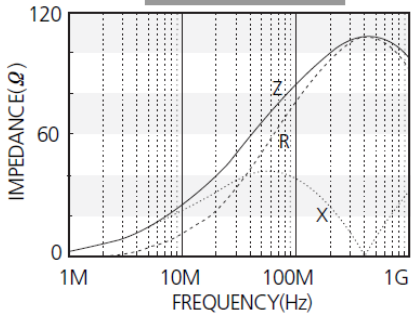
Part no.	Thickness (mm)	Impedance ( $\Omega$ )±25%@100MHz	DC Resistance ( $\Omega$ ) Max.	Rated Current (mA) Max.
CIB21P110	0.9±0.2	11	0.01	2000
CIB21P150	0.9±0.2	15	0.01	2000
CIB21P260	0.9±0.2	26	0.01	2000
CIB21P300	0.9±0.2	30	0.05	2000
CIB21P330	0.9±0.2	33	0.05	1500
CIB21P470	0.9±0.2	47	0.05	1500
CIM21U600	0.9±0.2	60	0.08	900
CIM21U800	0.9±0.2	80	0.10	900
CIM21U101	0.9±0.2	100	0.10	800
CIM21U121	0.9±0.2	120	0.10	800
CIM21U151	0.9±0.2	150	0.15	600
CIM21U241	0.9±0.2	240	0.15	600
CIM21U301	0.9±0.2	300	0.15	500
CIM21U471	0.9±0.2	470	0.30	500
CIM21U601	0.9±0.2	600	0.30	500
CIM21U102	0.9±0.2	1000(at 70MHz)	0.40	500
CIM21U202	0.9±0.2	2000(at 70MHz)	0.70	300

Part no.	Thickness (mm)	Impedance ( $\Omega$ ) $\pm$ 25% @100MHz	DC Resistance ( $\Omega$ ) Max.	Rated Current (mA) Max.
CIB21J260	0.9 $\pm$ 0.2	26	0.05	2000
CIB21J300	0.9 $\pm$ 0.2	30	0.05	2000
CIB21J400	0.9 $\pm$ 0.2	40	0.05	2000
CIM21J600	0.9 $\pm$ 0.2	60	0.08	900
CIM21J800	0.9 $\pm$ 0.2	80	0.08	1000
CIM21J121	0.9 $\pm$ 0.2	120	0.15	800
CIM21J151	0.9 $\pm$ 0.2	150	0.15	500
CIM21J221	0.9 $\pm$ 0.2	220	0.20	500
CIM21J241	0.9 $\pm$ 0.2	240	0.20	500
CIM21J301	0.9 $\pm$ 0.2	300	0.20	500
CIM21J471	0.9 $\pm$ 0.2	470	0.25	500
CIM21J601	0.9 $\pm$ 0.2	600	0.25	500
CIM21J102	0.9 $\pm$ 0.2	1000	0.35	500
CIM21J152	0.9 $\pm$ 0.2	1500(at 70MHz)	0.45	500
CIM21J182	0.9 $\pm$ 0.2	1800(at 70MHz)	0.45	500
CIM21J202	0.9 $\pm$ 0.2	2000(at 70MHz)	0.50	500
CIM21J222	0.9 $\pm$ 0.2	2200(at 70MHz)	0.70	300
CIM21J252	0.9 $\pm$ 0.2	2500(at 50MHz)	0.70	300
CIM21K152	0.9 $\pm$ 0.2	1500	0.45	300
CIM21K252	0.9 $\pm$ 0.2	2500	0.80	250
CIM21N700	0.9 $\pm$ 0.2	70	0.20	600
CIM21N121	0.9 $\pm$ 0.2	120	0.25	500
CIM21N241	0.9 $\pm$ 0.2	240	0.30	400

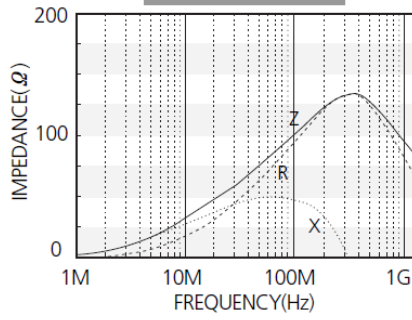
**CHARACTERISTIC DATA**



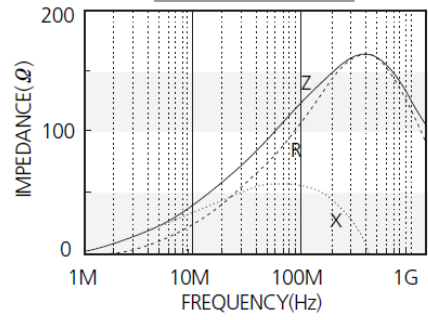
**CIM21U800**



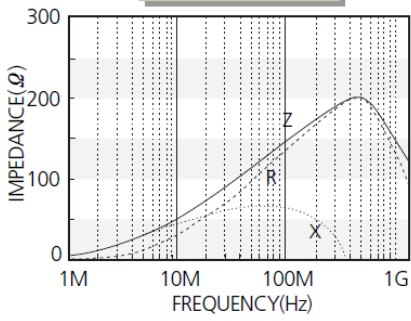
**CIM21U101**



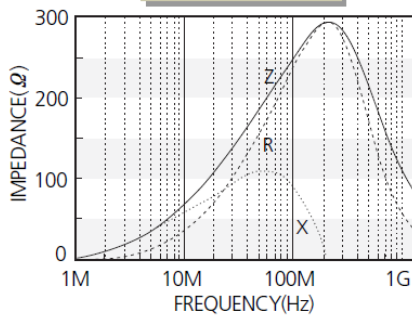
**CIM21U121**



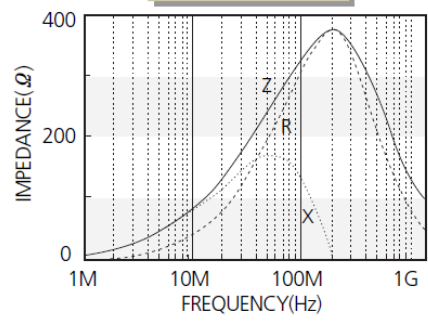
**CIM21U151**



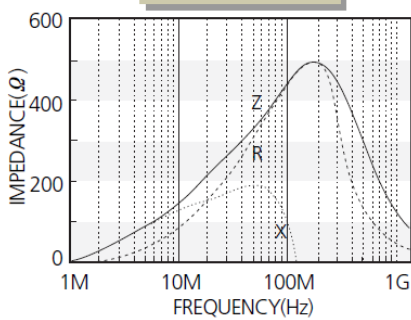
**CIM21U241**



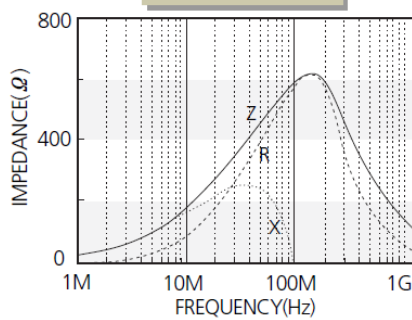
**CIM21U301**



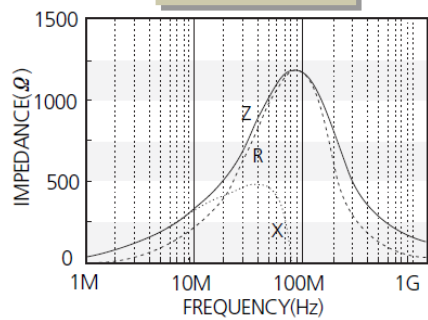
**CIM21U471**



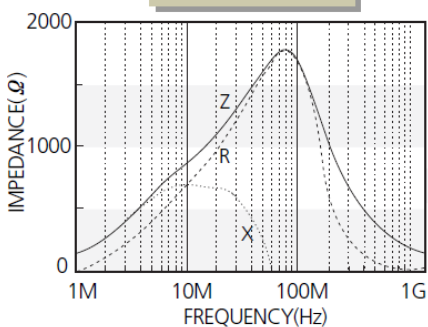
**CIM21U601**



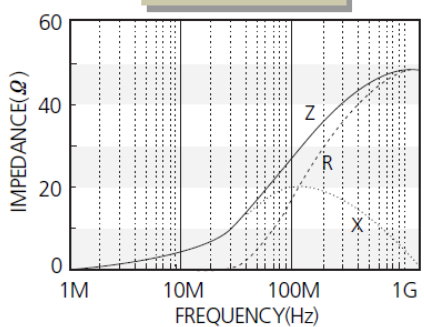
**CIM21U102**



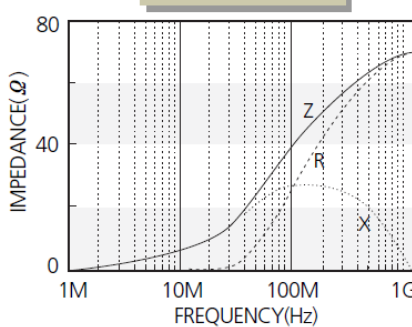
**CIM21U202**

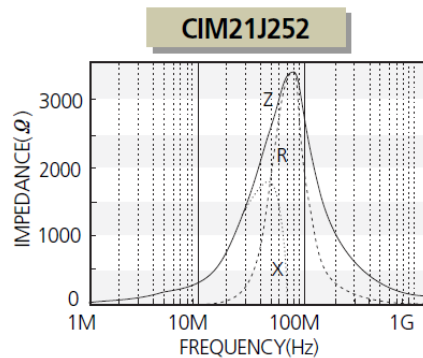
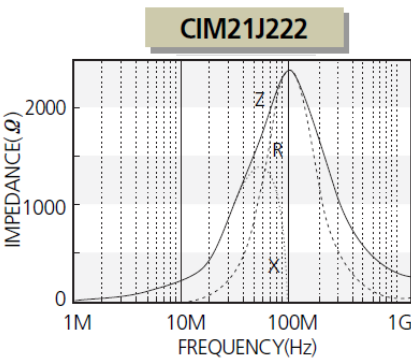
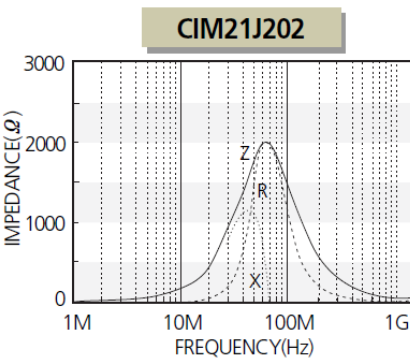
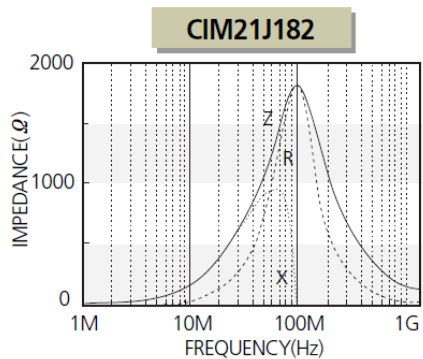
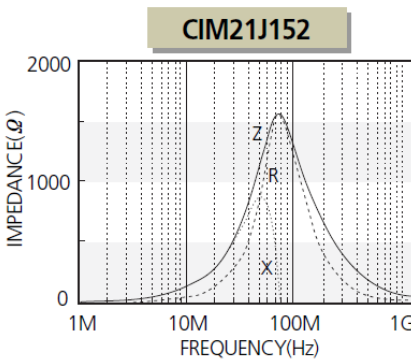
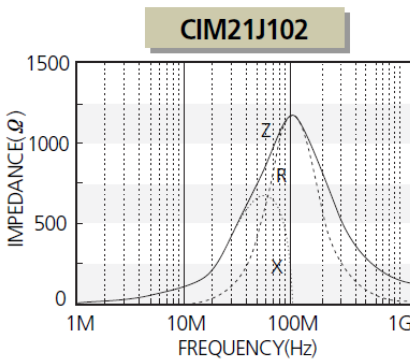
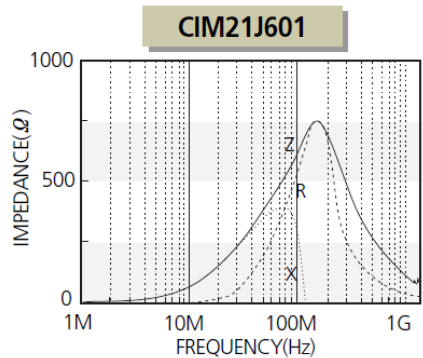
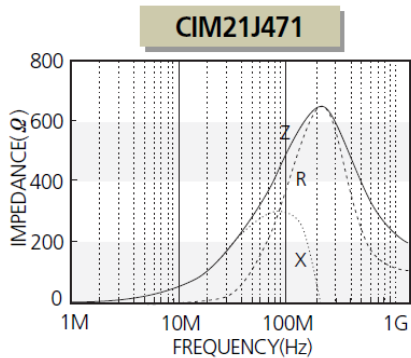
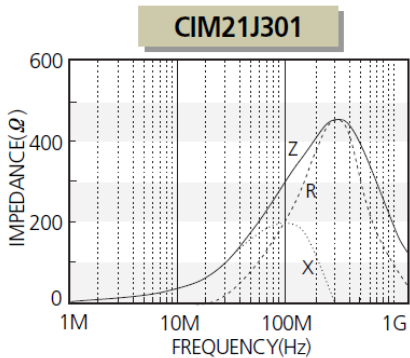
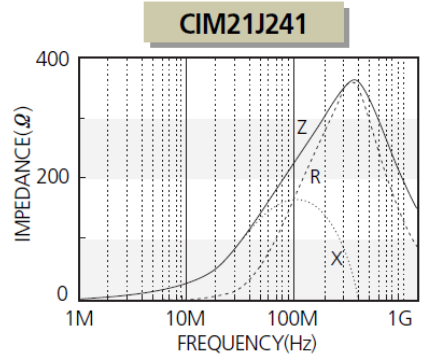
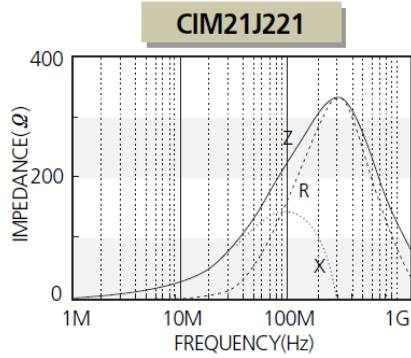
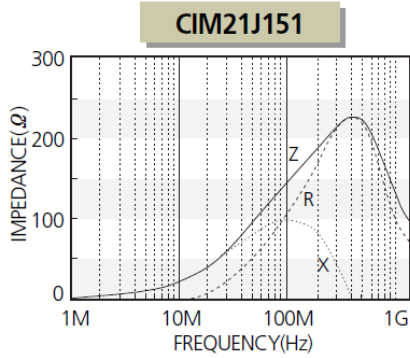
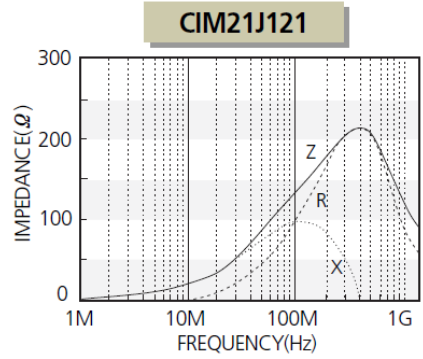
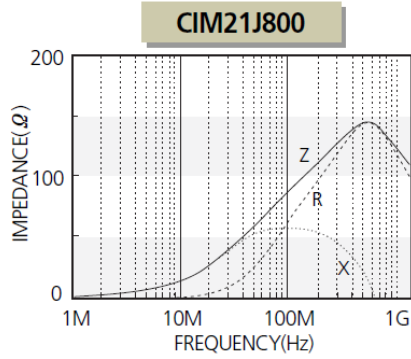
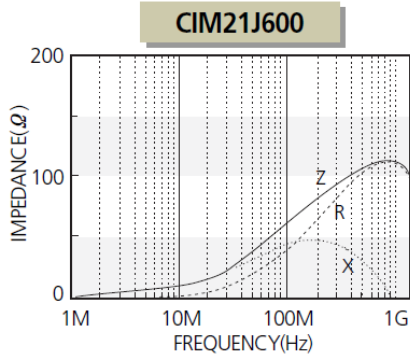


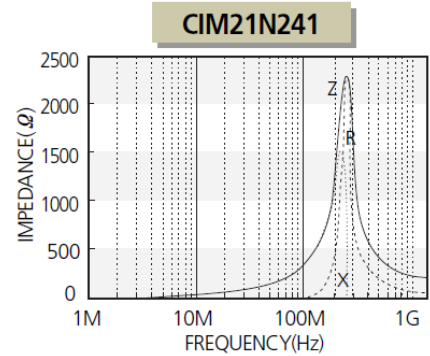
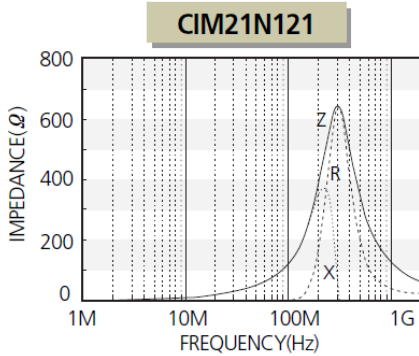
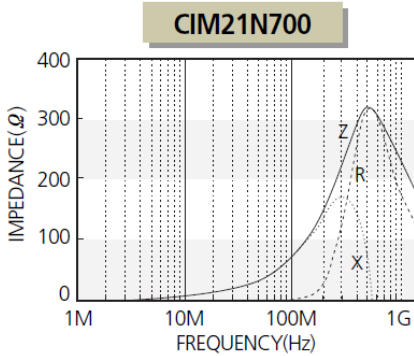
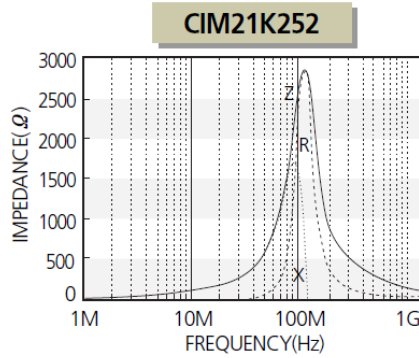
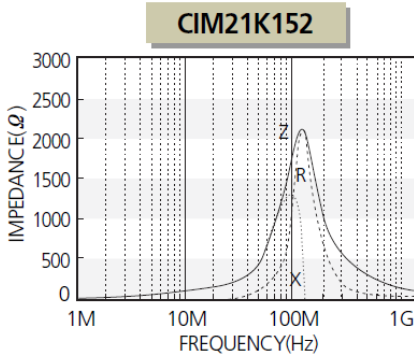
**CIB21J260**



**CIB21J400**







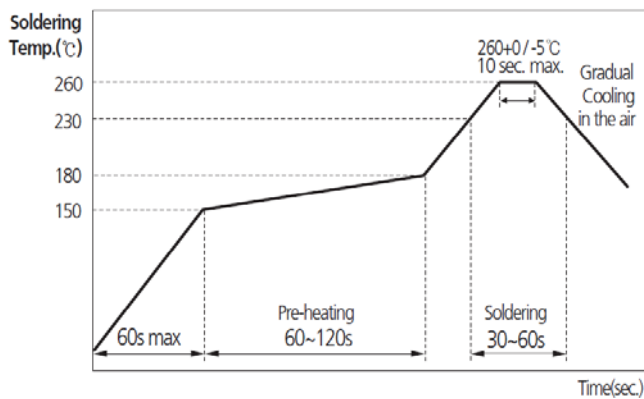
**PRODUCT IDENTIFICATION**

**C I M 21 U 121 N E**  
**(1) (2) (3) (4) (5) (6) (7)**

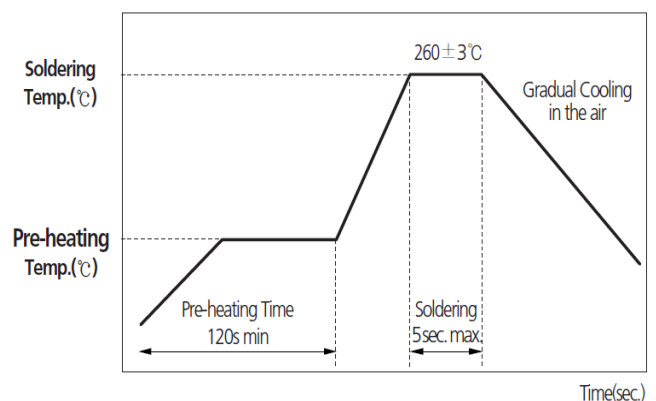
- (1) Chip Beads
- (2) M: Multi-layer type B:Mono-layer type
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (800:80Ω, 121:120Ω )
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

**RECOMMENDED SOLDERING CONDITION**

**REFLOW SOLDERING**



**FLOW SOLDERING**



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	4,000